

9. (New) A protection layer for a data recording medium, the protection layer comprising:  
a basic material; and  
a compound having a thermal conductivity greater than or equal to 10 W/m.deg  
when in a bulk state, said compound comprising magnesium oxide in a molar ratio with the basic  
material of 3% to 45% magnesium oxide.

10. (New) A protection layer for a data recording medium, the protection layer comprising:  
a basic material; and  
a compound having a thermal conductivity greater than or equal to 10 W/m.deg  
when in a bulk state, said compound comprising yttrium oxide in a molar ratio with the basic  
material of 10% to 80% yttrium oxide.

11. (New) A protection layer for a data recording medium, the protection layer comprising:  
a basic material; and  
a compound having a thermal conductivity greater than or equal to 10 W/m.deg  
when in a bulk state, said compound comprising gallium nitride in a molar ratio with the basic  
material of 1% to 30% gallium nitride.

12. (New) A protection layer for a data recording medium, the protection layer comprising:  
a basic material; and  
a compound having a thermal conductivity greater than or equal to 10 W/m.deg  
when in a bulk state, said compound comprising silicon nitride in a molar ratio with the basic  
material of 10% to 85% silicon nitride.

13. (New) A protection layer for a data recording medium, the protection layer comprising:  
a basic material; and

a compound having a thermal conductivity greater than or equal to 10 W/m.deg when in a bulk state, said compound comprising aluminum nitride in a molar ratio with the basic material of 1% to 50% aluminum nitride.

B' 14. (New) A protection layer for a data recording medium, the protection layer comprising:  
a basic material; and

a compound having a thermal conductivity greater than or equal to 10 W/m.deg when in a bulk state, said compound comprising a silicon carbide in a molar ratio with the basic material of 5% to 50% silicon carbide.

15. (New) A protection layer for a data recording medium, the protection layer comprising:  
a basic material; and

a compound having a thermal conductivity greater than or equal to 10 W/m.deg when in a bulk state, said compound comprising a titanium carbide in a molar ratio with the basic material of 10% to 85% titanium carbide.--

---

03/11/04 14:00